

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4852182

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHENZHEN HUAWEI TECHNOLOGIES SOFTWARE CO., LTD.	02/27/2018
RECEIVING PARTY DATA	
Name:	HUAWEI TECHNOLOGIES CO., LTD.
Street Address:	HUAWEI ADMINISTRATION BUILDING
Internal Address:	BANTIAN, LONGGANG DISTRICT
City:	SHENZHEN
State/Country:	CHINA
Postal Code:	518129
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15058783
CORRESPONDENCE DATA	
Fax Number:	(972)628-3616
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	972-628-3600
Email:	patents@munckwilson.com
Correspondent Name:	DOCKET CLERK/HTCL
Address Line 1:	P.O. DRAWER 800889
Address Line 4:	DALLAS, TEXAS 75380
ATTORNEY DOCKET NUMBER:	HUAW06-07679
NAME OF SUBMITTER:	ROBERT D. MCCUTCHEON
SIGNATURE:	/ROBERT D. MCCUTCHEON/
DATE SIGNED:	03/06/2018
Total Attachments: 1	
source=Assignment#page1.tif	

ASSIGNMENT AGREEMENT

WHEREAS, SHENZHEN HUAWEI TECHNOLOGIES SOFTWARE CO., LTD., of Huawei Administration Building, Bantian, Longgang District, Shenzhen, 518129, Guangdong, P.R. China, hereinafter referred to as "Assignor" is the owner of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: SERVICE PATH PROTECTION METHOD, CONTROLLER, DEVICE AND SYSTEM
Filing Date: 3/2/2016
Application No.: 15058783

WHEREAS, HUAWEI TECHNOLOGIES CO., LTD., a corporation of China, located at Huawei Administration Building, Bantian, Longgang District, Shenzhen, 518129, Guangdong, P.R. China, hereinafter referred to as "Assignee", is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable considerations, receipt of which is hereby acknowledged by Assignor, Assignor has assigned, and by these presents do assign to Assignee all right, title, and interest in and to the invention and application and to all foreign counterparts (including patent, utility mode and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignor had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees that it will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

This ASSIGNMENT AGREEMENT is hereby agreed by both Assignee and Assignor, and comes into effect on the date when the Assignee signs this ASSIGNMENT AGREEMENT, or the date when the Assignor signs This ASSIGNMENT AGREEMENT, whichever is later.

For and on behalf of Assignor by: [Signature] Date: Feb 27, 2018
Yun DING
Title: President of SHENZHEN HUAWEI TECHNOLOGIES SOFTWARE CO., LTD.

For and on behalf of Assignee by: [Signature] Date: Feb 27, 2018
Yafeng SUN
Title: President of HUAWEI TECHNOLOGIES CO., LTD.